

Progress on Instrumentation and its impact on EF

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U.S. DEPARTMENT OF
ENERGY

Office of Science



SLAC

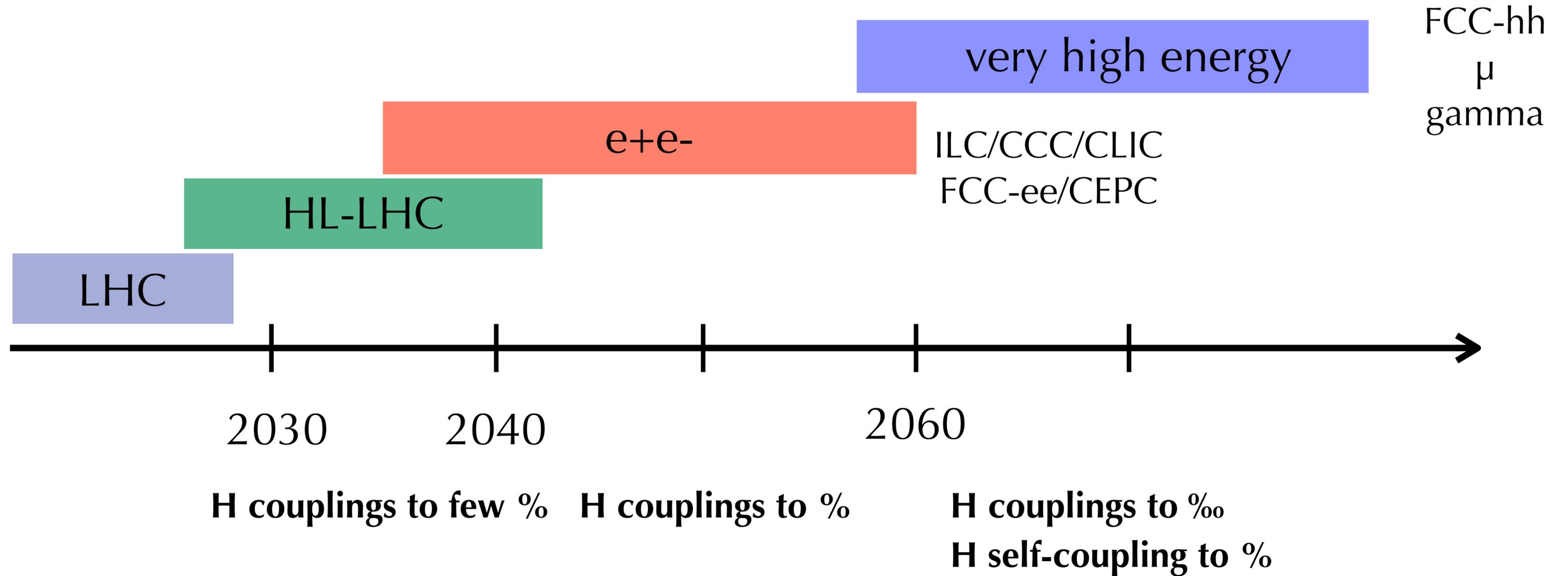
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EF drivers for detector developments

- The transformative physics goals include 4 inspiring & distinct directions:
 - Higgs properties @ sub-%
 - Higgs self-coupling @ 5%
 - Higgs connection to DM
 - New multi-TeV particles
- Technical requirements mostly from existing detector proposals.
 - The muon collider's detector requirements are still being developed

Science	Measurement	Technical Requirement (TR)	PRD
Higgs properties with sub-percent precision	TR 1.1: Tracking for e^+e^-	TR 1.1.1: p_T resolution: $\sigma_{p_T}/p_T = 0.2\%$ for central tracks with $p_T < 100$ GeV, $\sigma_{p_T}/p_T^2 = 2 \times 10^{-5}/\text{GeV}$ for central tracks with $p_T > 100$ GeV	18, 19, 20, 23
Higgs self-coupling with 5% precision		TR 1.1.2: Impact parameter resolution: $\sigma_{r\phi} = 5 \oplus 15 (p [\text{GeV}] \sin^{\frac{3}{2}}\theta)^{-1} \mu\text{m}$	
Higgs connection to dark matter	TR 1.2: Tracking for 100 TeV pp	Generally same as e^+e^- (TR 1.1) except TR 1.2.1: Radiation tolerant to 300 MGy and $8 \times 10^{17} \text{ n}_{\text{eq}}/\text{cm}^2$ TR 1.2.2: $\sigma_{p_T}/p_T = 0.5\%$ for tracks with $p_T < 100$ GeV TR 1.2.3: Per track timing resolution of 5 ps rejection and particle identification	16, 17, 18, 19, 20, 23, 26
New particles and phenomena at multi-TeV scale	TR 1.3: Calorimetry for e^+e^-	TR 1.3.1: Jet resolution: 4% particle flow jet energy resolution TR 1.3.2: High granularity: EM cells of $0.5 \times 0.5 \text{ cm}^2$, hadronic cells of $1 \times 1 \text{ cm}^2$ TR 1.3.3: EM resolution : $\sigma_E/E = 10\%/\sqrt{E} \oplus 1\%$ TR 1.3.4: Per shower timing resolution of 10 ps	1, 3, 7, 10, 11, 23
	TR 1.4: Calorimetry for 100 TeV pp	Generally same as e^+e^- (TR 1.3) except TR 1.4.1: Radiation tolerant to 4 (5000) MGy and $3 \times 10^{16} (5 \times 10^{18}) \text{ n}_{\text{eq}}/\text{cm}^2$ in endcap (forward) electromagnetic calorimeter TR 1.4.2: Per shower timing resolution of 5 ps	1, 2, 3, 7, 9, 10, 11, 16, 17, 23, 26
	TR 1.5: Trigger and readout	TR 1.5.1: Logic and transmitters with radiation tolerance to 300 MGy and $8 \times 10^{17} \text{ n}_{\text{eq}}/\text{cm}^2$ TR 1.5.2: Total throughput of 1 exabyte per second at 100 TeV pp collider	16, 17, 21, 26

Looking to the future



Which collider?

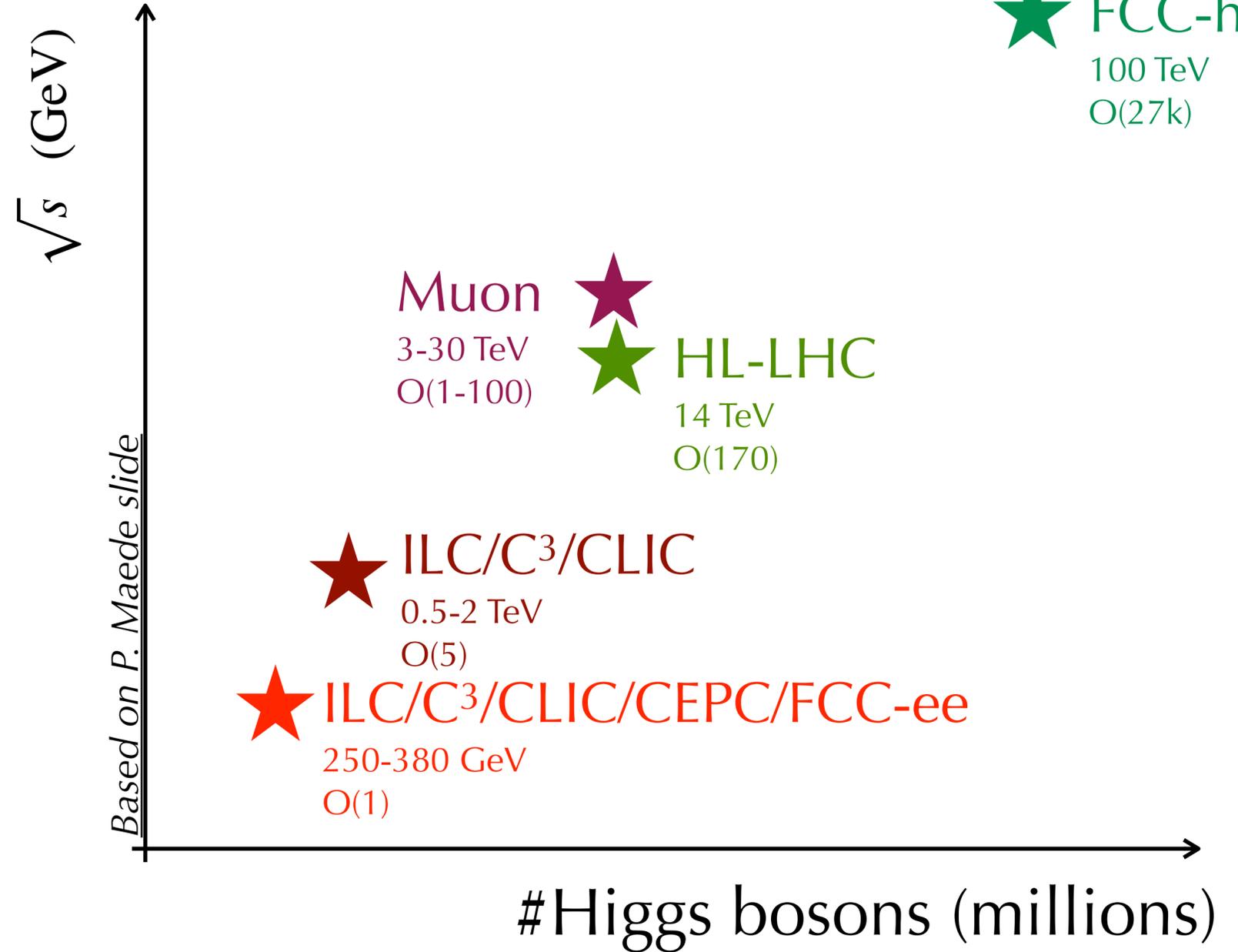
LEPTON COLLIDERS

- **Circular e+e-** (CEPC, FCC-ee)
 - **90-350 GeV**
 - *strongly limited by synchrotron radiation above 350– 400 GeV*
- **Linear e+e-** (ILC, CLIC, C³)
 - **250 GeV — 3TeV**
 - *Reach higher energies, and can use polarized beams*
 - *Relatively low radiation / beam induced backgrounds*
 - *C³ plans is to run at 250/550 GeV*
[C3 proposal - talk on Wed](#)
- $\mu+\mu-$
 - **3-30 TeV**

HADRON COLLIDERS

- **75-200 TeV** (FCC-hh)

PROJECT READINESS IS VERY DIFFERENT



Which collider?

LEPTON COLLIDERS

- **Circular e+e-** (CEPC, FCC-ee)
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PROJECT READINESS IS VERY DIFFERENT

\sqrt{s} (GeV)

★ FCC-hh
100 TeV
O(27k)

Muon ★
3-30 TeV

*Several collider options being studied to go beyond HL-LHC
Different colliders probe different dominant processes with their own experimental challenges
And also project readiness is VERY different*

C3 proposal - talk on Wed

- $\mu+\mu-$
 - **3-30 TeV**

HADRON COLLIDERS

- **75-200 TeV** (FCC-hh)

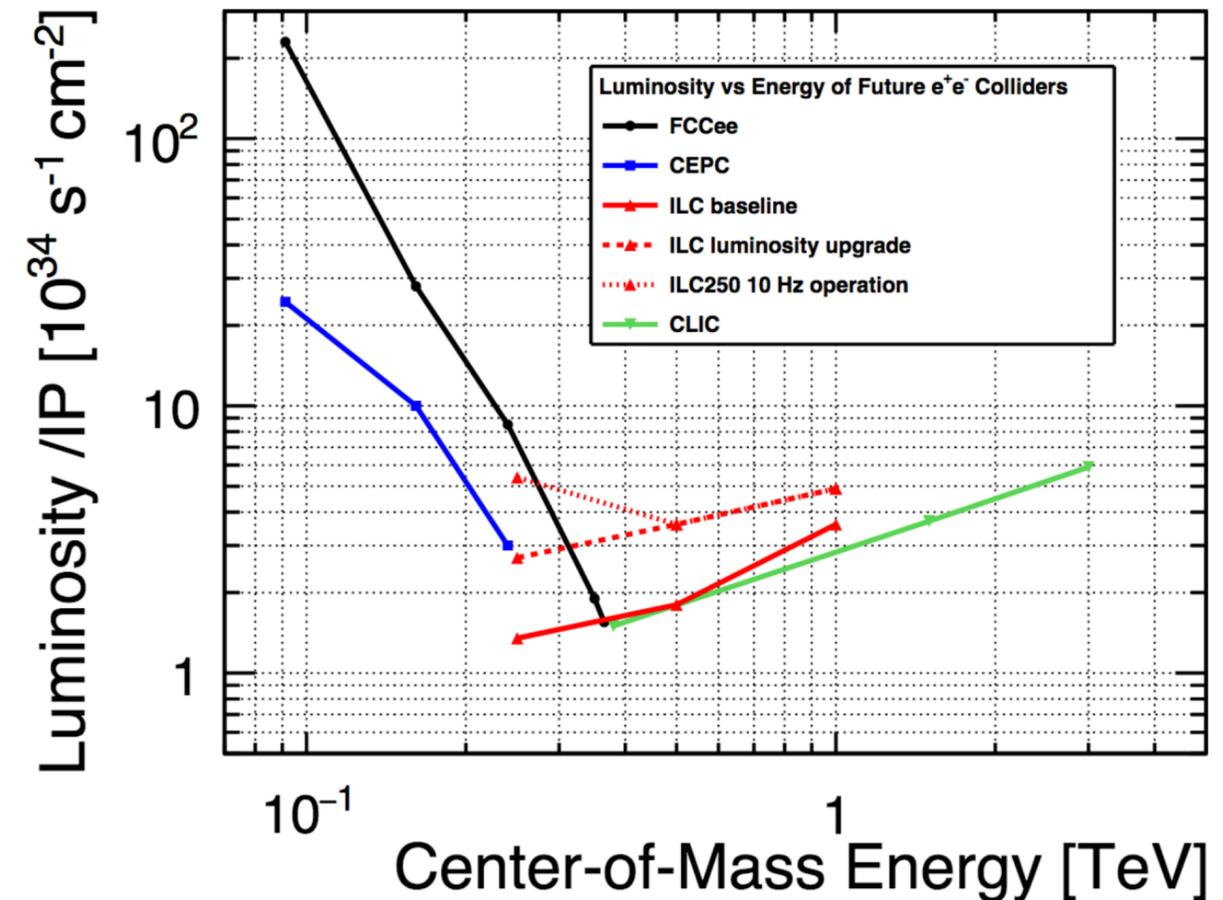
Based on

★ ILC/C³/CLIC/CEPC/FCC-ee
250-380 GeV
O(1)

#Higgs bosons (millions)

Linear & Circular Lepton Colliders

- **Linear e+e-** colliders: ILC, CCC, CLIC
 - Reach higher energies, and can use polarized beams
 - Relatively low radiation / beam induced backgrounds
 - Collisions in bunch trains
 - Power pulse - Turn off detector in between trains
 - Significant power saving → easier to cool detectors
- **Circular e+e-** colliders: FCC-ee, CEPC
 - Highest luminosity collider at Z / WW / Zh, energy limited by synchrotron radiation
 - No power pulsing → detectors need active cooling → more material in detector
 - Beam continues to circulate after collision → Limits magnetic field in detectors to 2T
- **Muon Collider**
 - Potential to reach high energy: 10 TeV range → Technology readiness?
 - Luminosity → muon decay in flight
 - Beam induced backgrounds → significant challenge, even at low energy



Higgs physics as a driver for future detectors R&D

- The goal of measuring Higgs properties with sub-% precision translates into ambitious requirements for tracker, calorimeters and timing detectors at e+e-
- Advancing HEP detectors to new regimes of sensitivity
- Building next-generation HEP detectors with novel materials & advanced techniques

Tracking

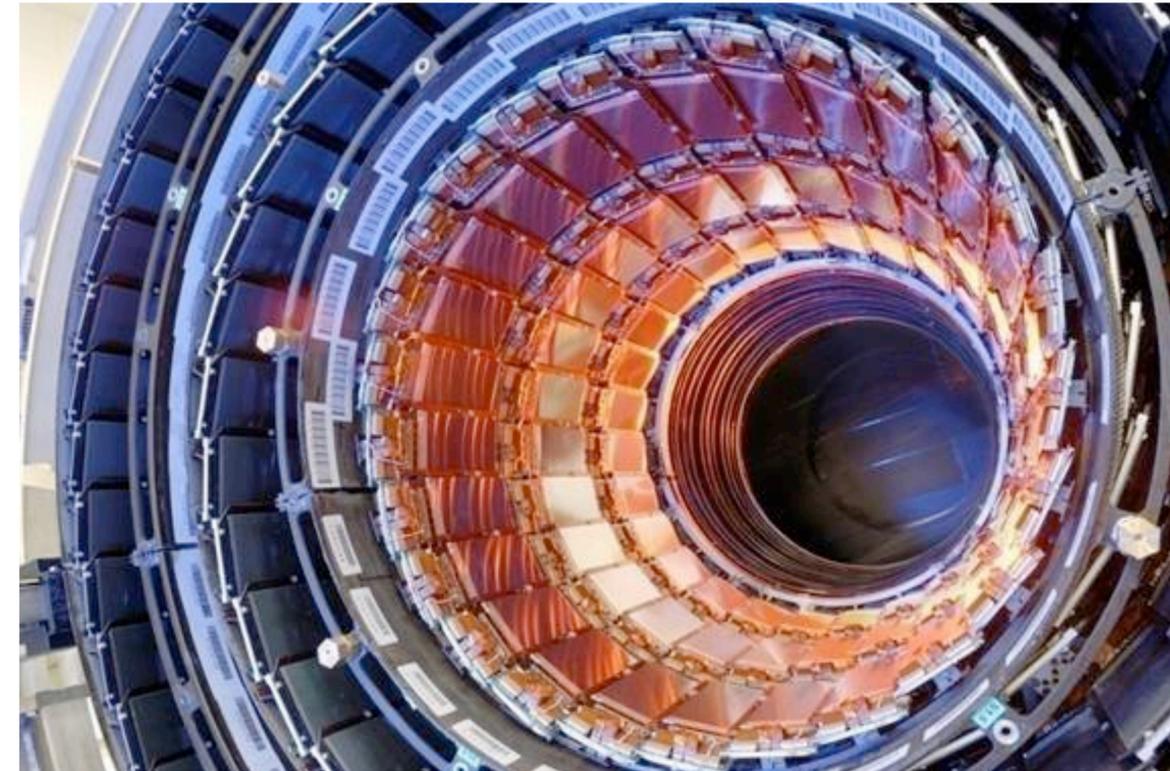
Calorimetry

Measurement	Technical Requirement (TR)
TR 1.1: Tracking for e^+e^-	TR 1.1.1: p_T resolution: $\sigma_{p_T}/p_T = 0.2\%$ for central tracks with $p_T < 100$ GeV, $\sigma_{p_T}/p_T^2 = 2 \times 10^{-5}/\text{GeV}$ for central tracks with $p_T > 100$ GeV TR 1.1.2: Impact parameter resolution: $\sigma_{r\phi} = 5 \oplus 15 (p [\text{GeV}] \sin^{\frac{3}{2}}\theta)^{-1} \mu\text{m}$ TR 1.1.3: Granularity : $25 \times 50 \mu\text{m}^2$ pixels TR 1.1.4: $5 \mu\text{m}$ single hit resolution TR 1.1.5: Per track timing resolution of 10 ps
TR 1.3: Calorimetry for e^+e^-	TR 1.3.1: Jet resolution: 4% particle flow jet energy resolution TR 1.3.2: High granularity: EM cells of $0.5 \times 0.5 \text{ cm}^2$, hadronic cells of $1 \times 1 \text{ cm}^2$ TR 1.3.3: EM resolution : $\sigma_E/E = 10\%/\sqrt{E} \oplus 1\%$ TR 1.3.4: Per shower timing resolution of 10 ps

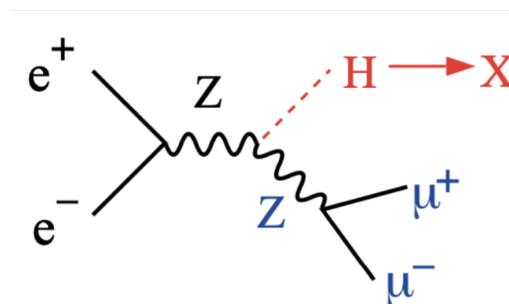
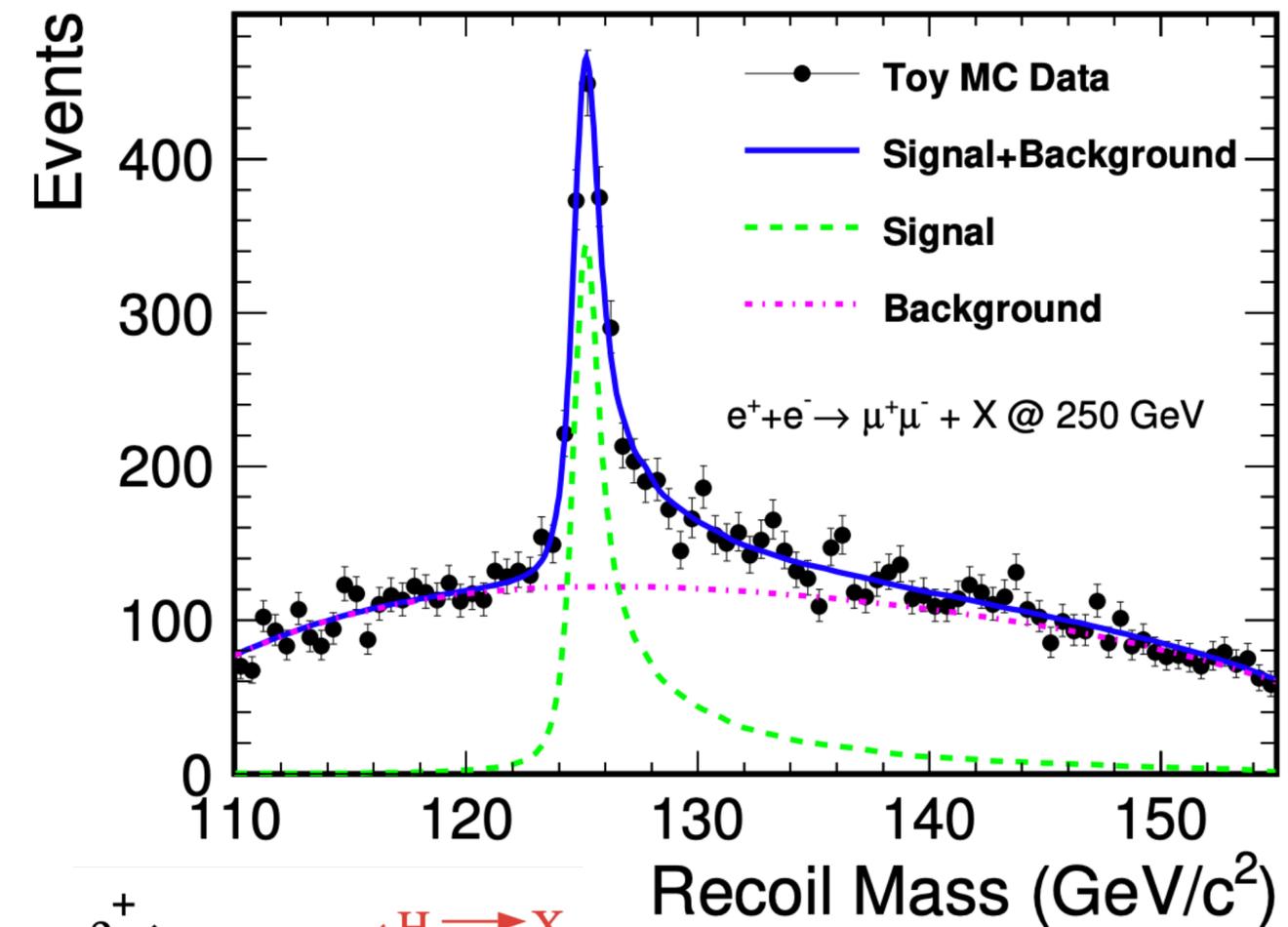
DOE Basic Research Needs Study on Instrumentation

The Central Role of Tracking at e+e-

- Tracking detectors provide the primary measurements for charged particle momentum and impact parameter
 - Momentum and IP resolution are limiting factors in key precision measurements
- Detector systems at Lepton Colliders designed for **Particle Flow reconstruction**
- Primary, Secondary, and Tertiary vertex reconstruction
 - Key for identifying and separating heavy flavor jets
- Bunch crossing time stamping, leads to reduction of beam backgrounds

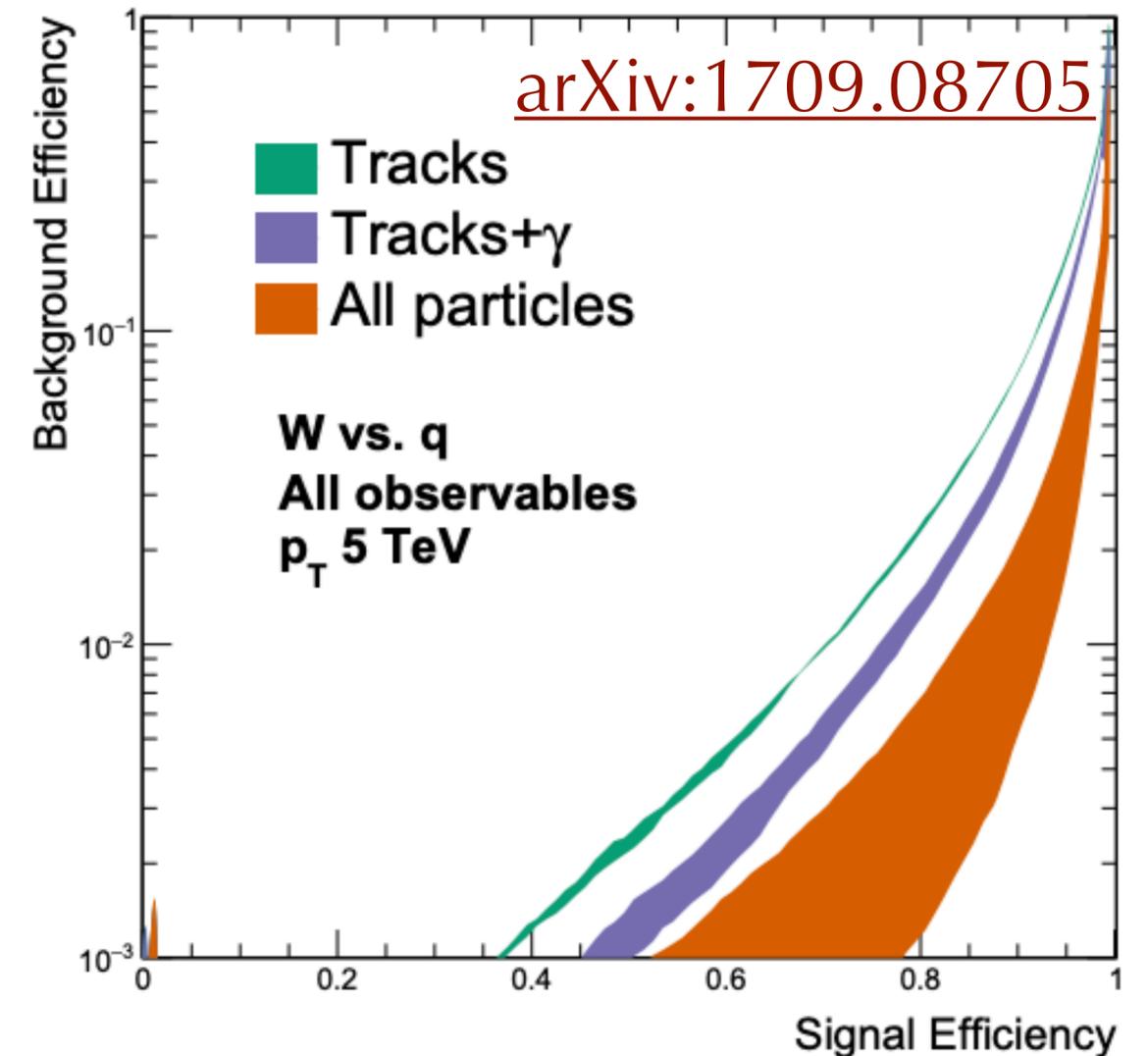


- **ZH process:** Higgs recoil reconstructed from $Z \rightarrow \mu\mu$
 - Drives requirement on charged track momentum and jet resolutions
 - Sets need for high field magnets and high precision / low mass trackers
 - Bunch time structure allows high precision trackers with very low X_0 at **linear lepton colliders**
- **Higgs \rightarrow bb/cc decays:** Flavor tagging & quark charge tagging at unprecedented level
 - Drives requirement on charged track impact parameter resolution \rightarrow low mass trackers near IP
 - $<0.3\%$ X_0 per layer (ideally 0.1% X_0) for vertex detector
 - Sensors will have to be less than $75 \mu\text{m}$ thick with at least $5 \mu\text{m}$ hit resolution ($17\text{-}25\mu\text{m}$ pitch)



Need new generation of ultra low mass vertex detectors with dedicated sensor designs

- **Boosted/Substructure object reconstruction** is an important driver to guide detector design at future multi-TeV machines
 - pixel hit merging as one of the limiting factors
 - Also any improvement in tracking will directly impact jet reconstruction and calibration, particle-flow
- **Long Lived Particle searches** could be an important benchmark for timing/trigger Study of min radius for (few layers of) tracking detectors at future colliders
 - “Acceptance” for non-prompt charged particles at future detectors

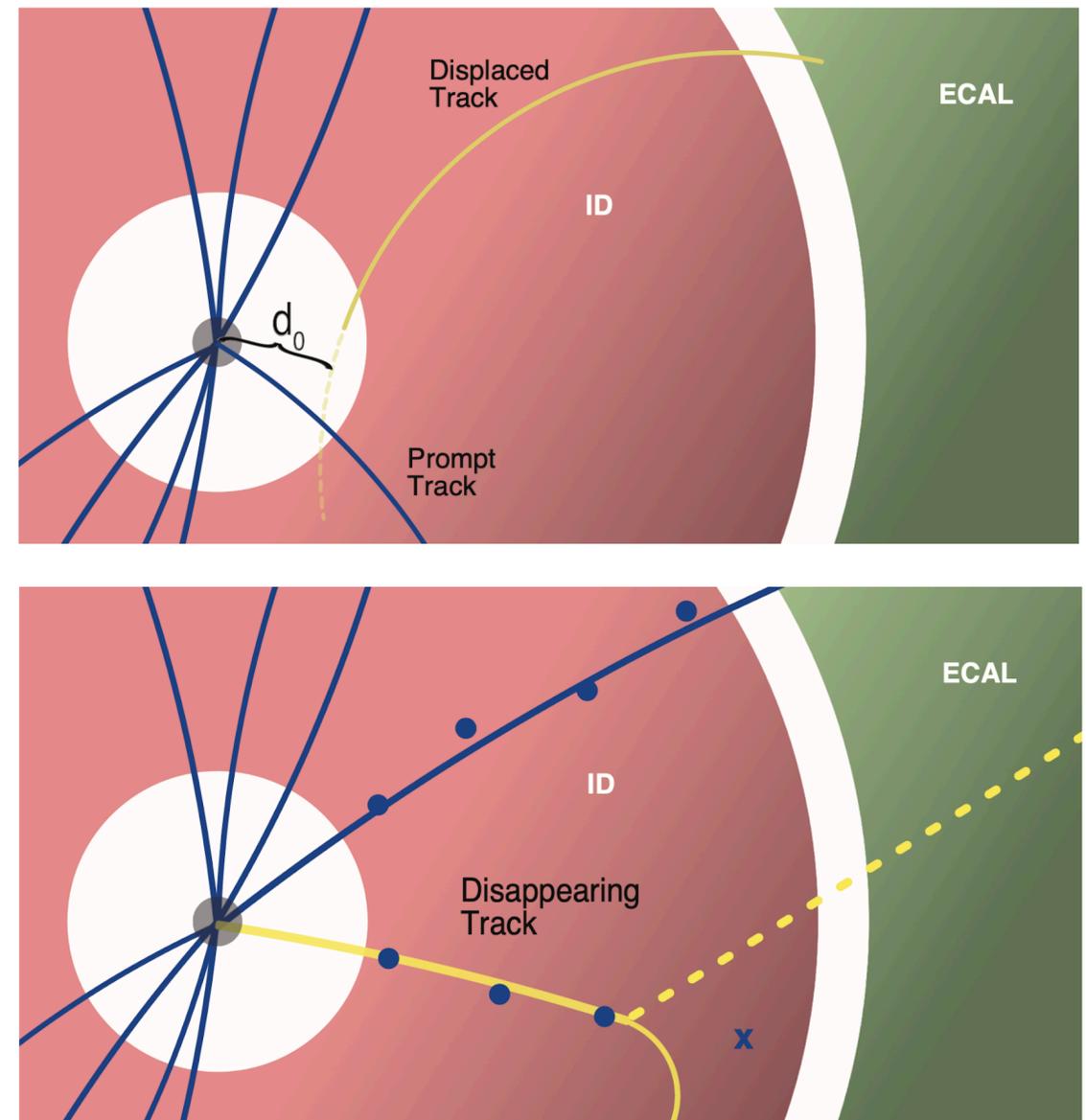


Dedicated discussion at the CPM Oct, 2020

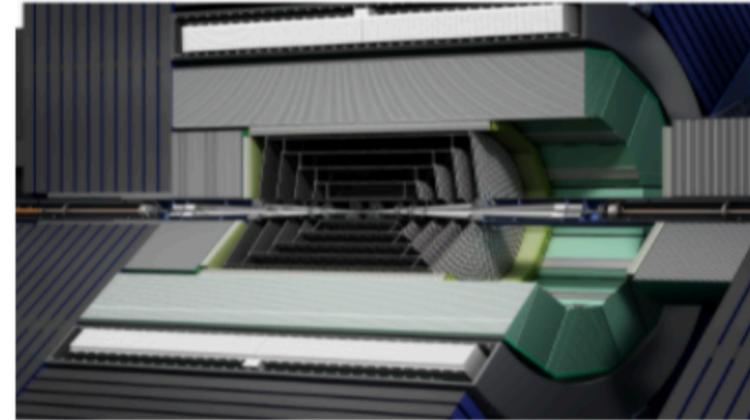
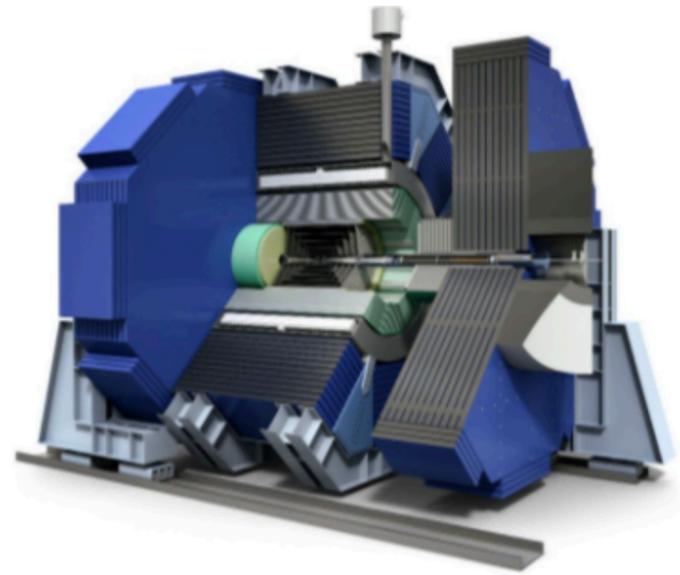
LLP requirements

- Different **geometry** choices that provide similar hermeticity for prompt particles can differ drastically in their coverage of particles not originating at the interaction point
- Interplay of **geometry** choice with hermeticity, trigger-capabilities, and even data-rate reduction need to keep in mind LLP needs
- High **granularity** at large radius: ability for precision-tracking at outer radii
- Identifying decays of LLP in various sub-systems away from the interaction point and distinguish them from detector-specific backgrounds (including beam-induced backgrounds)
- Measurement of ionization energy loss and timing can boost **particle ID** capabilities and offer unique handles for LLP direct identification
 - Depending on environment, one can also explore the advantages of TPCs or a mixed TPC+Si system to allow identification of LLP-specific signatures
 - E.g. kinked track, or good measurement of ionization energy loss

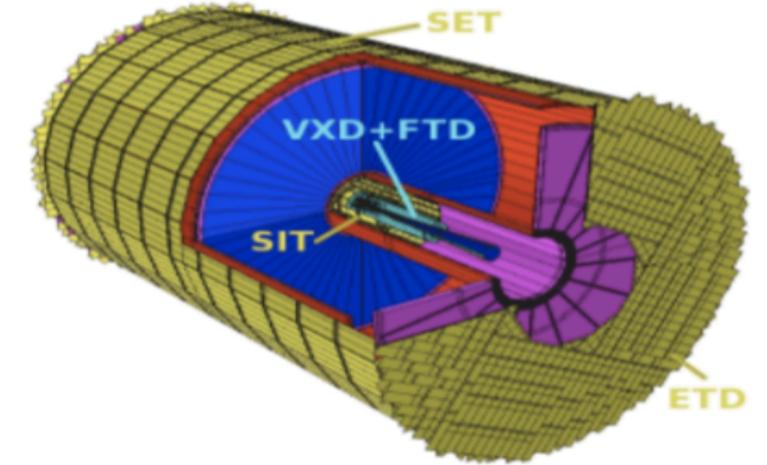
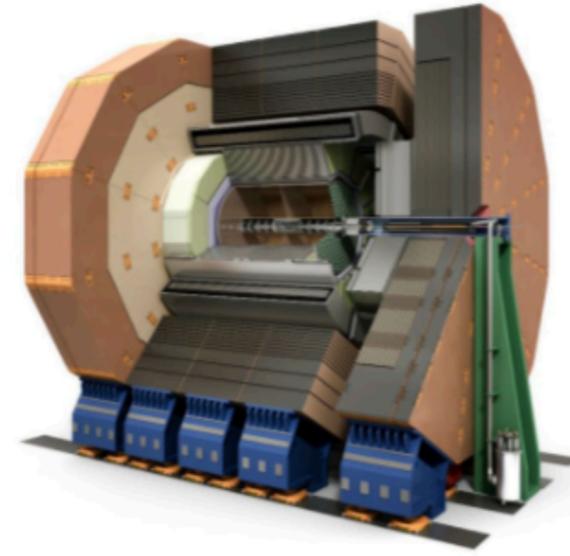
CPM Oct, 2020



Detectors design at lepton colliders



SiD



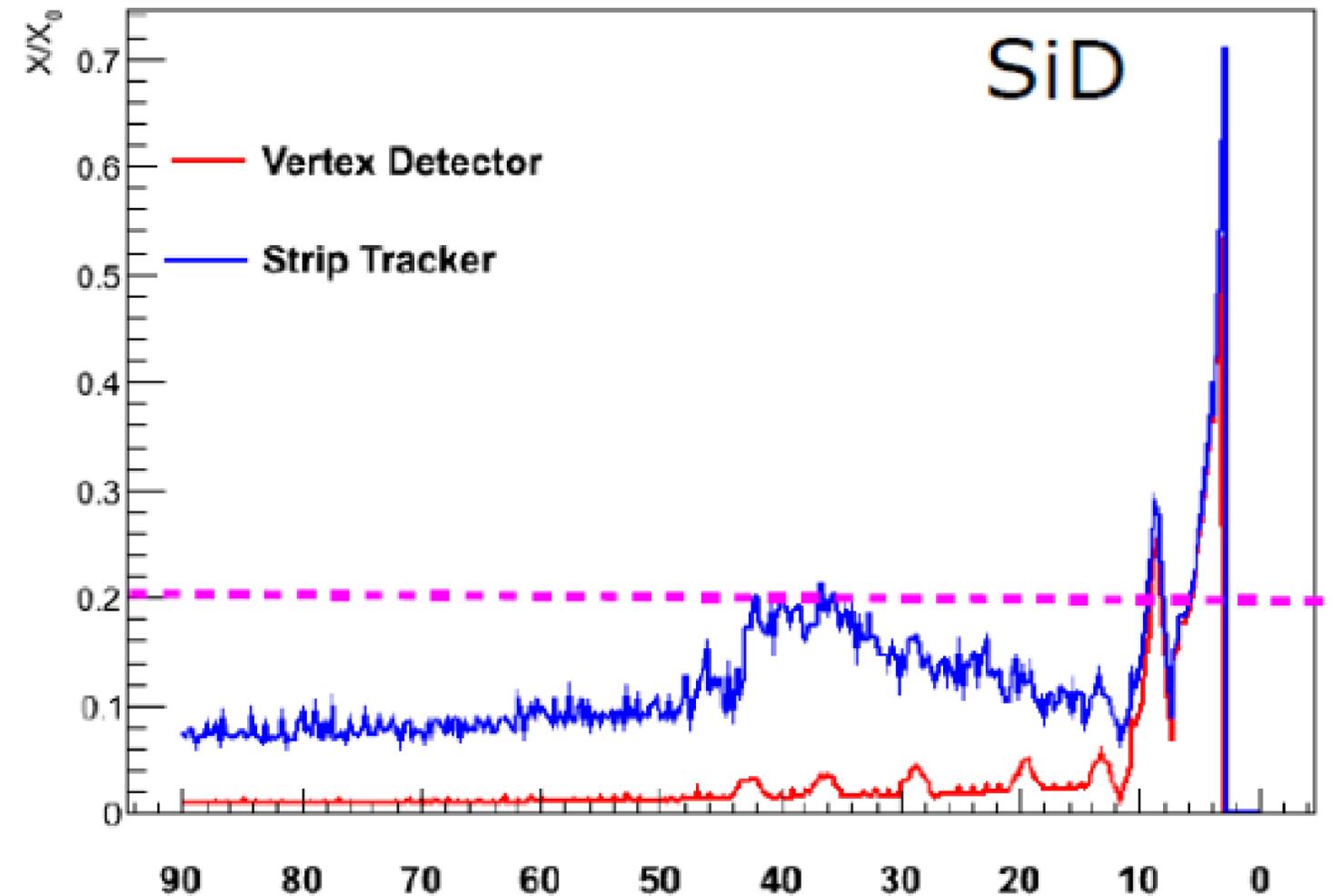
ILD

- Detector designs at e+e- colliders are converging to very similar strategies
 - Particle Flow reconstruction → plays a big part in many designs
- SiD like detector - Compact all silicon detector
- ILD like detector - Larger detector with Silicon+TPC tracker
 - Larger detector. Simulation and design work active in Europe / Japan
- IDEA detector - Using dual readout calorimeter, under study at CEPC/FCC-ee

Physics Drivers → Detector Design Requirements

Requirements on single point resolution, location of innermost layer, detector occupancy

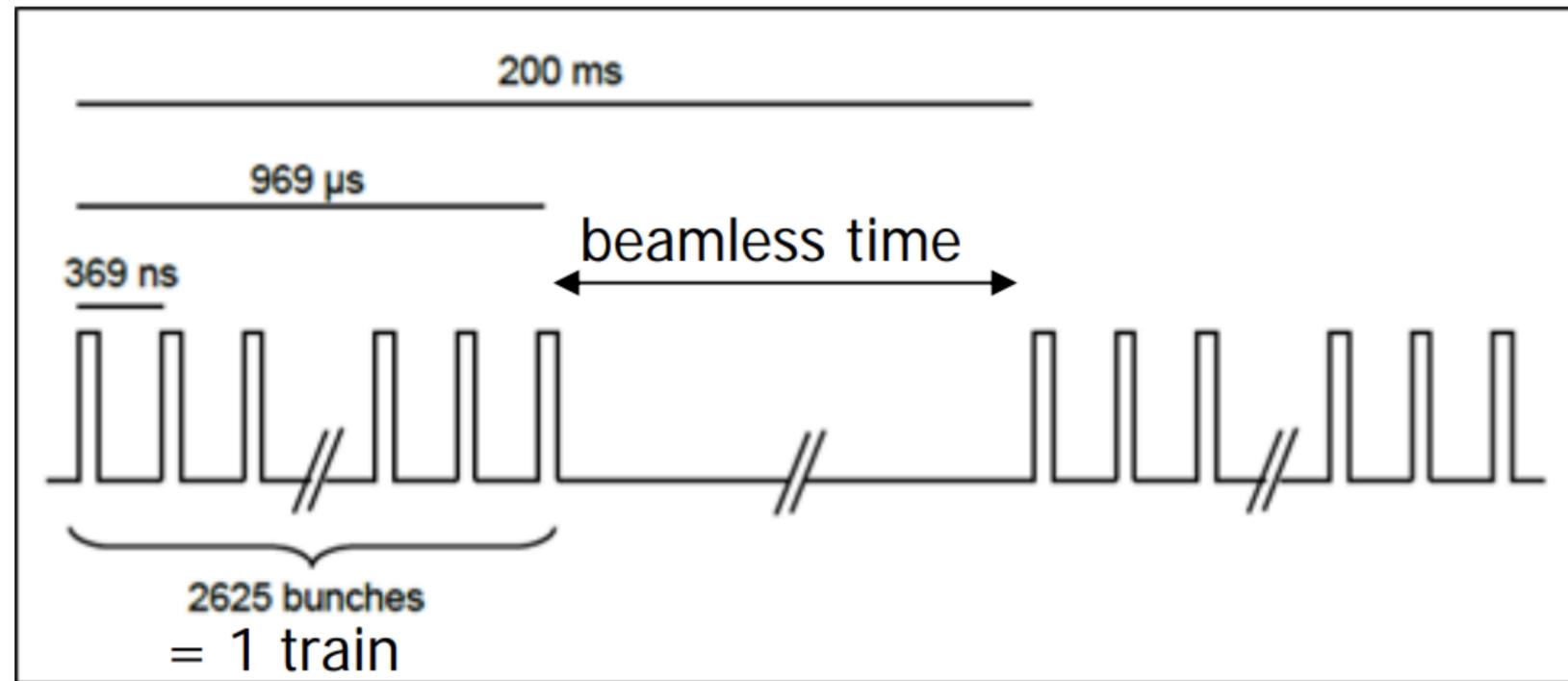
- **Very small pixels** for excellent IP resolution and minimal pattern recognition ambiguity
- **Minimal material** as close to the interaction point as possible:
 - $<0.3\%$ X_0 per layer (ideally 0.1% X_0) for vertex detector
 - $<1\%$ X_0 per layer for Si-tracker
- **Low power** → Linear colliders eliminate need for active cooling, circular collider do not



Physics Drivers → Detector Design Requirements

Linear Collider timing structure: Fraction of a percent duty cycle

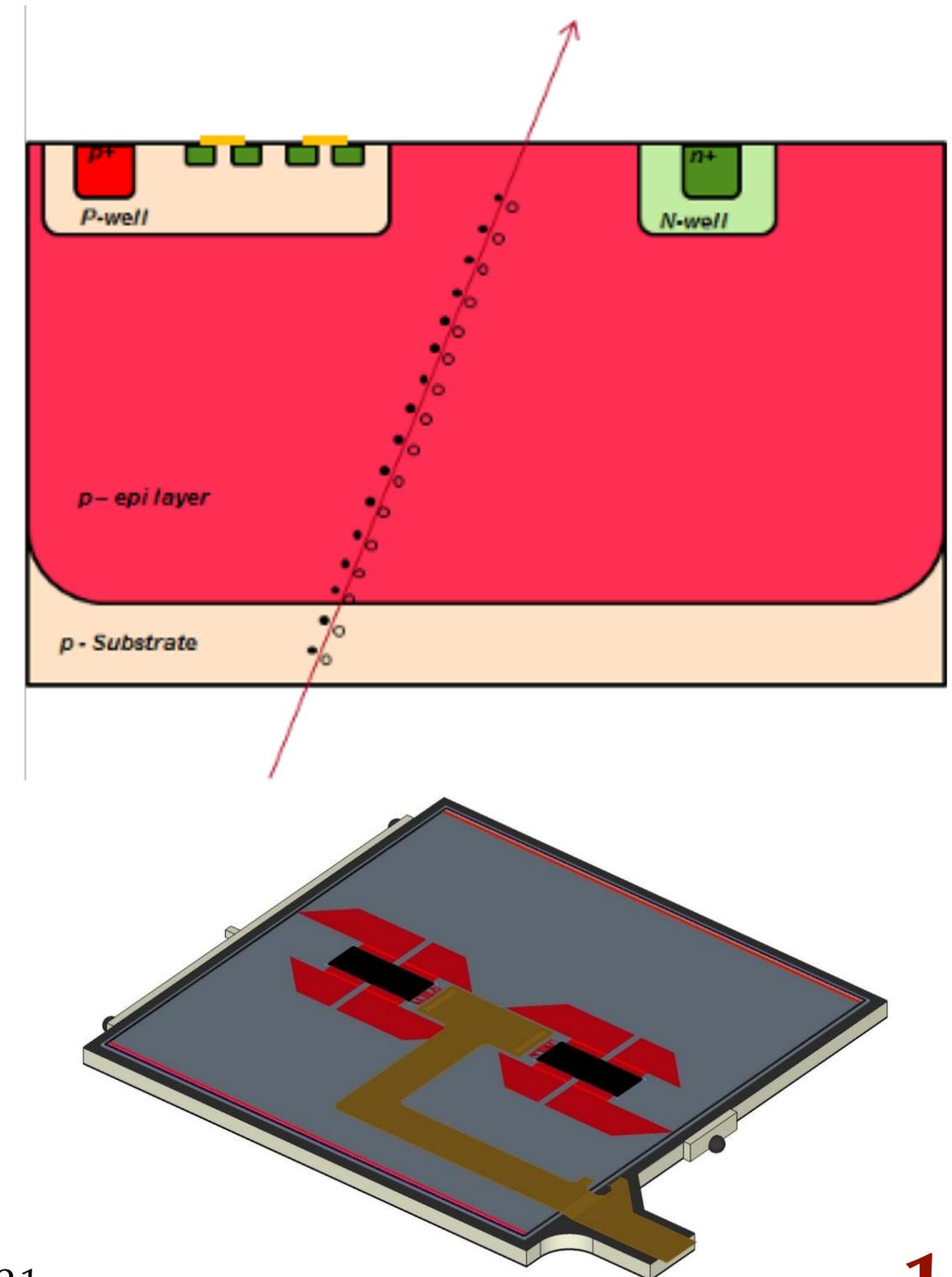
- **Power pulsing possible**, significantly reduce heat load
 - Factor of 50-100 power saving for FE analog power
- Si vertexing & tracking detectors **don't need active cooling**
 - Significantly lowers mass budget
- **Triggerless readout** is the baseline



1 ms long bunch trains at 5 Hz
2820 bunches per train
308ns spacing (ILC TDR)

MAPS for SiD tracker detector

- Monolithic technologies have the potential for providing higher granularity, thinner, intelligent detectors at lower overall cost.
- Significantly **lower material budget**: sensors and readout electronics are integrated on the same chip
- Eliminate the need for bump bonding and can be thinned to less than 100 μm
- Smaller pixel size, not limited by bump bonding
- Lower costs - can be implemented in standard commercial CMOS technologies
- Over the past decade, SiD has developed a first generation of sensors, readout with KPiX
 - 25 x 100 μm^2 pixels

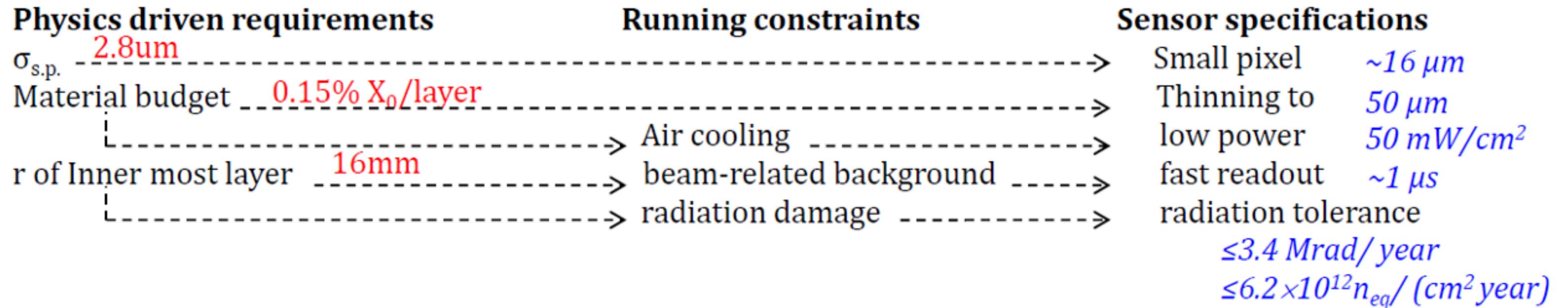


Sensors technology requirements for Vertex Detector

Several technologies are being studied to meet the physics performance :

sensors will have to be less than 75 μm thick with at least 3-5 μm hit resolution (17-25 μm pitch) and low power consumption:

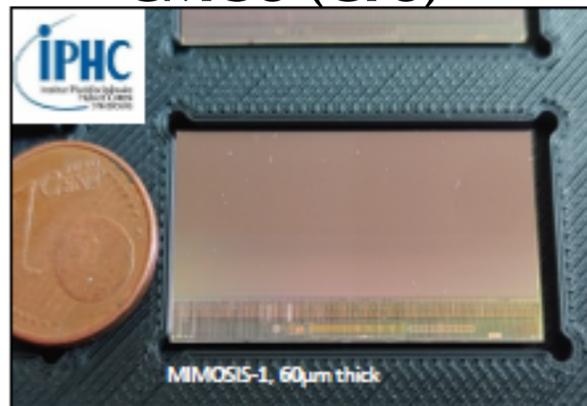
- continuous r/o during the train with power cycling
- delayed after the train \rightarrow either $\sim 5\mu\text{m}$ pitch for occupancy or in-pixel time-stamping



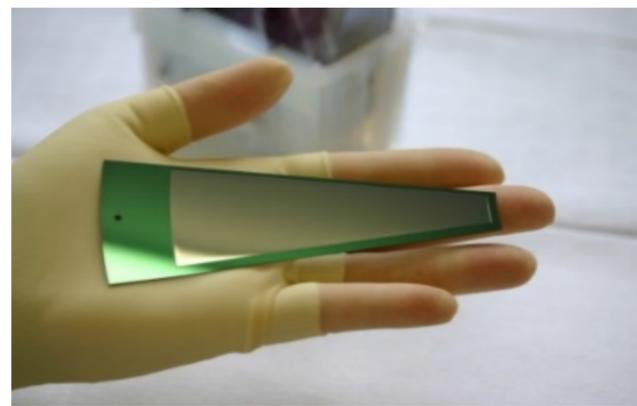
Several possible choices for the VTX detector:

- Monolithic Active Pixels (MAPS)
 - CMOS Pixel Sensors (CPS)
 - Fully Depleted on High Resistivity Substrate (DNwel sensing)
 - Fully Depleted SOI technologies
- Depleted Field Effect Transistors (DEPFET)
- Fine pixel Charged Coupled Devices (CCD)
- 3D integration
- The general landscape is also changing rapidly with advances in microelectronics

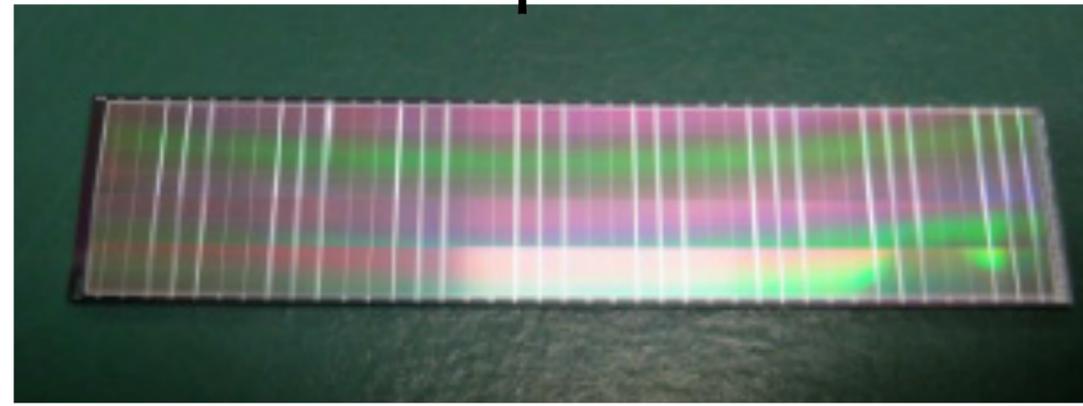
CMOS (CPS)



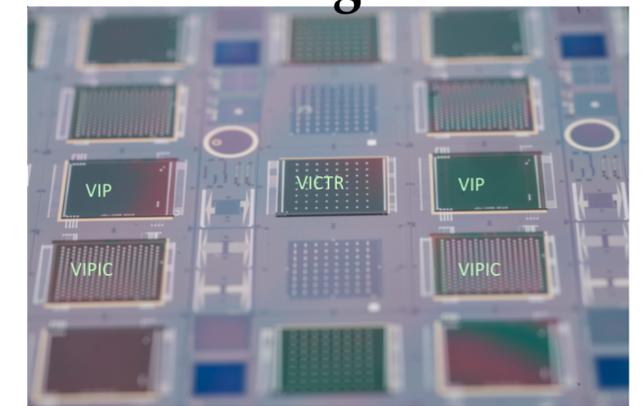
DEPFET



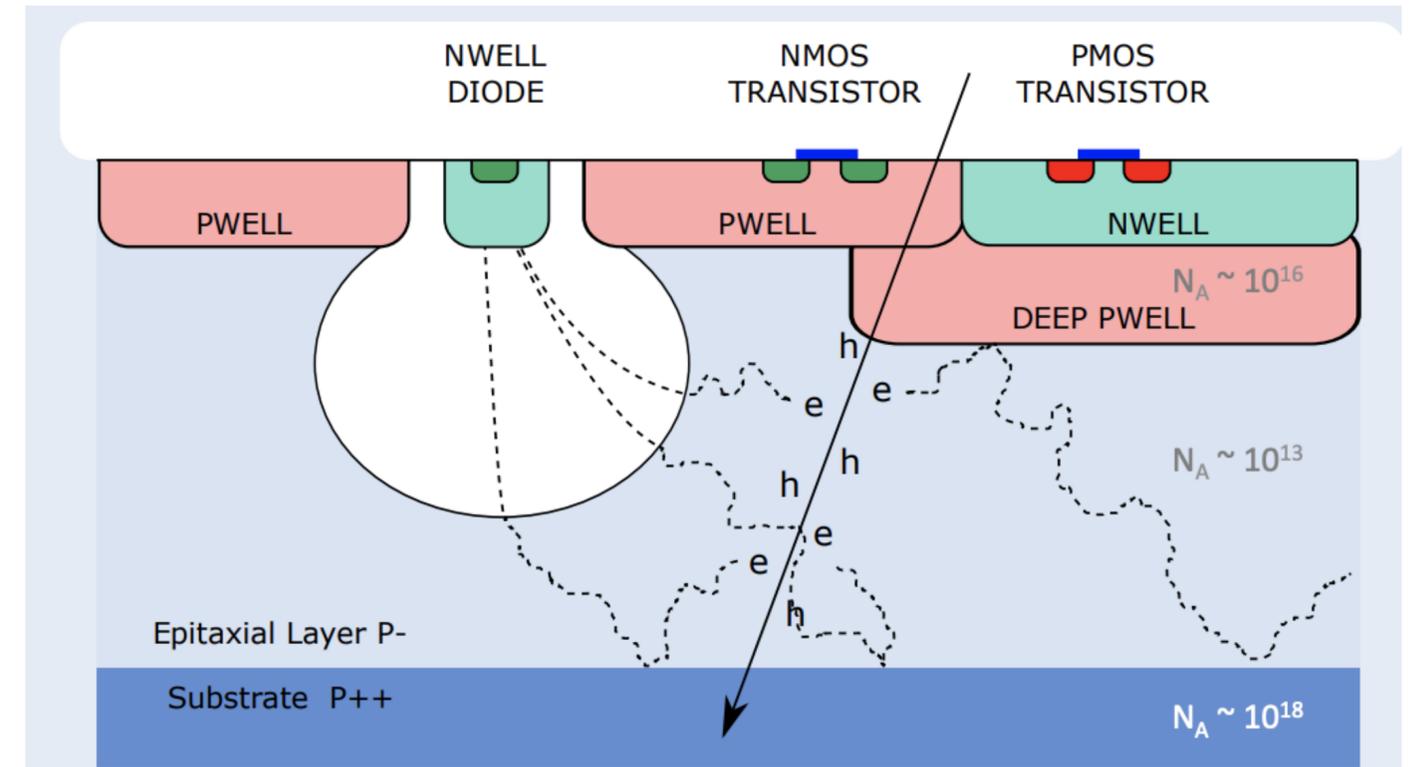
Fine pixel CCD



3D Integration

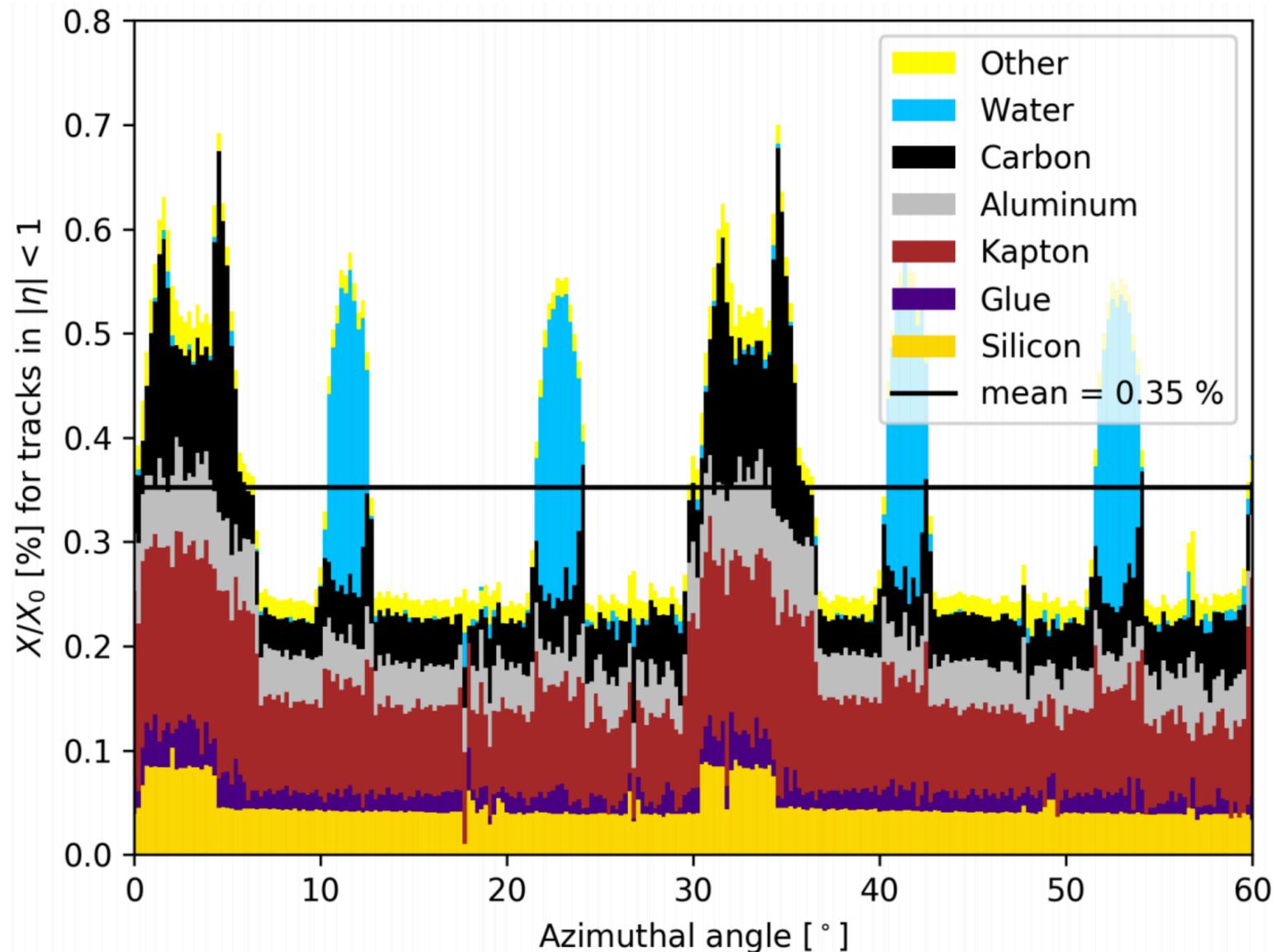


- With the current tracker upgrade ALICE redefined the new state-of-the-art in CMOS MAPS technology and its applications in HEP
- ALICE Pixel DEtector (ALPIDE) uses CMOS Pixel sensor used in imaging process
 - full CMOS circuitry within active area
 - Sensor thickness = 20-40 μm (0.02-0.04% X0)
 - 5 μm spatial resolution
 - radiation hard to 10^{13} 1 MeV n_{eq}

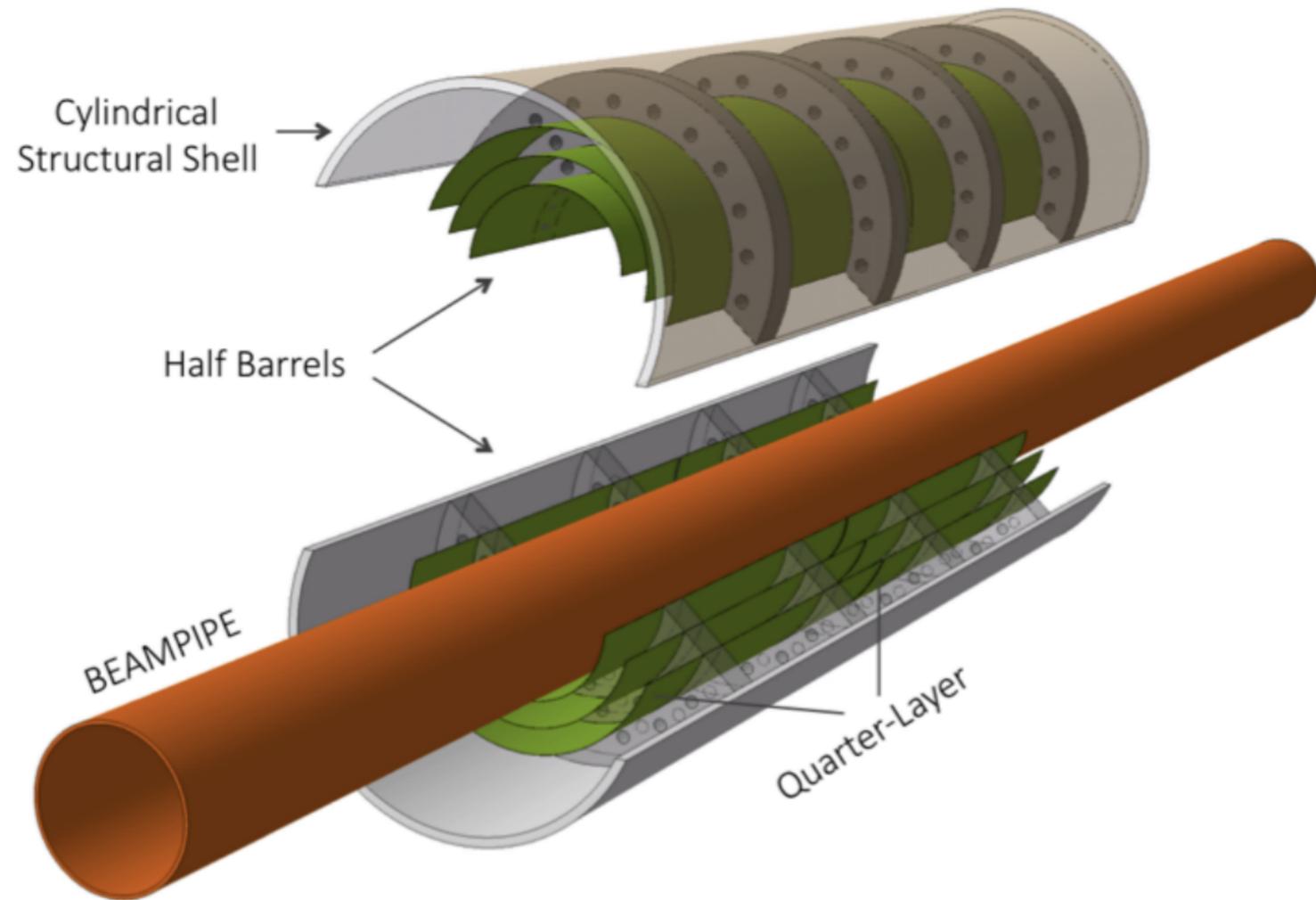


V. Manzari, 2019

The used technology offers further opportunities: smaller feature size, **bending** that directly impact the key measurements that highly rely on precise vertexing and low material budget



- Sensor's contribution to the total material budget is 15-30%
- cables + cooling + support make up most of the detector mass
- Challenges (beam backgrounds, cooling, material budget) needs to be addressed by emerging R&D's:
 - Reduce impact of mechanical supports, services, overlap of modules/ladders
 - Beam related background suppression \implies evolve time stamping toward a few 100 ns (bunch-tagging)
- At linear colliders the baseline consists in air-cooling which is expected to be able to extract the total power dissipation of the vertex detector ($< 40 \text{ mW/cm}^2$)
 - more specific developments are also being pursued as micro-channel cooling for DEPFET



Bending Si wafers + circuits is possible

Recent ultra-thin wafer-scale silicon technologies allow:

Sensor thickness = 20-40 μm - 0.02-0.04% X0

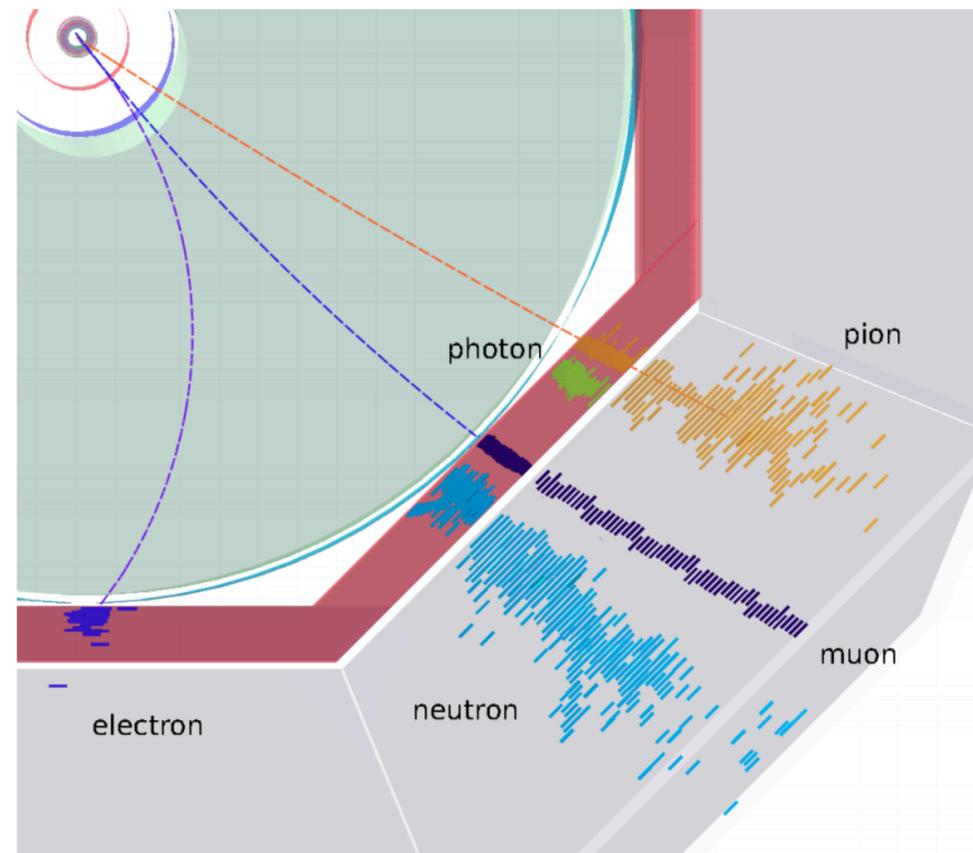
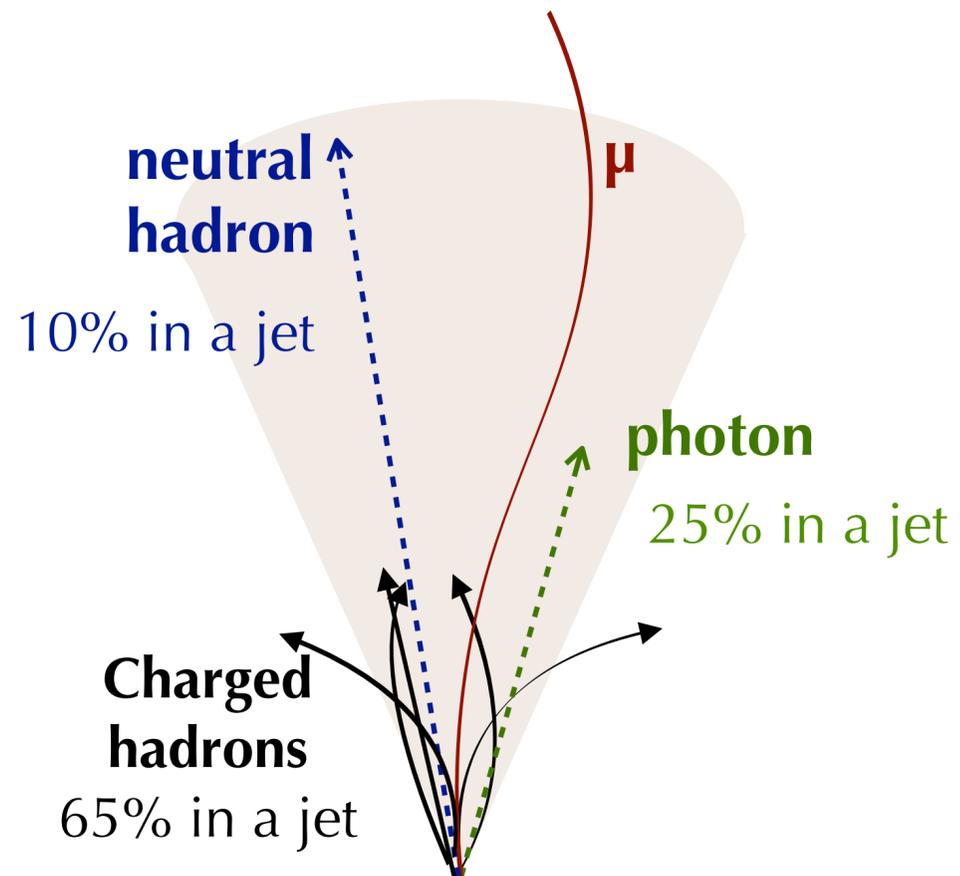
Sensors arranged with a perfectly cylindrical shape

a sensors thinned to $\sim 30\mu\text{m}$ can be curved to a radius of 10-20mm (ALICE-PUBLIC-2018-013)

Industrial stitching & curved CPS along goals of ALICE-ITS3, possibly with 65 nm process

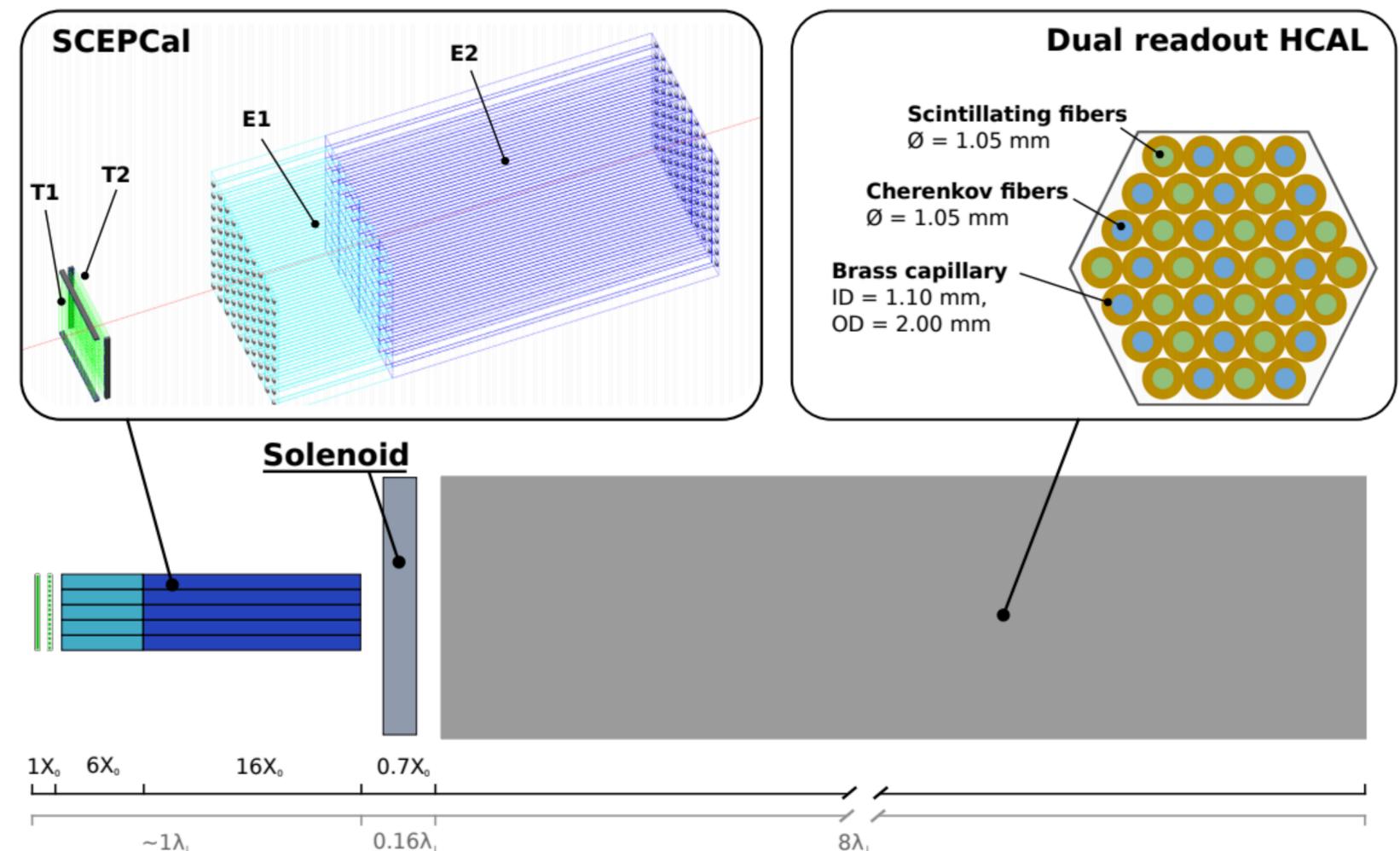
Particle Flow Calorimeters

- CALICE collaboration: development and study of finely segmented and imaging calorimeters
 - Precise reconstruction of each particle within the jet
 - Issues: overlap between showers, complicated topology, separate physics event particles from beam-induced background
- CALICE R&D inspired CMS high granularity solution HGCal - Common test beams with the AHCAL prototype
 - New ideas/technologies being explored: high precision (ps) timing calorimeters and new sensors ideas (ex: MAPS, LGADs)



- **Dual readout Calorimetry**, e.g. DREAM (FCC-ee, CePC) improvement of the energy resolution of hadronic calorimeters for single hadrons:
 - Cherenkov light for relativistic (EM) component
 - Scintillation light for non-relativistic (hadronic)
- Sensible improvement in jet resolution using dual-readout information combined with a particle flow approach → 3-4% for jet energies above 50 GeV

[Marco Lucchini, EPS 2021](#)



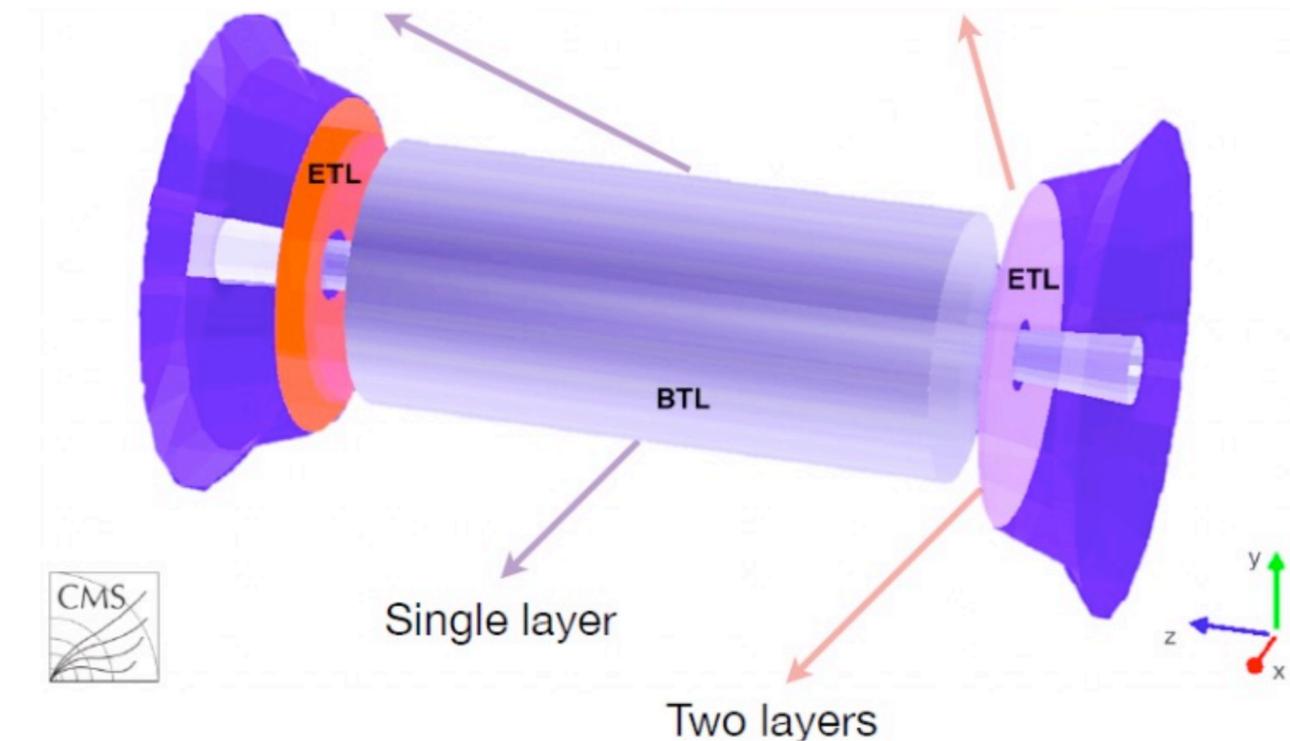
Timing detectors with a $O(10)$ picosecond resolution

Hadron Colliders:

- 4D pattern recognition for HL-LHC pile-up rejection: tracking $\sim O(10's)$ μm & timing detectors $\sim O(10's)$ ps
- ATLAS HGTD, CMS ETL (LGAD)
- CMS BTL (LYSO +SiPM)
- ps-timing reconstruction in calorimetry: resolve development of hadron showers, triangulate H to photons primary vertices
- CMS HGCAL (Si & Sci.+SiPMs)

Future challenges:

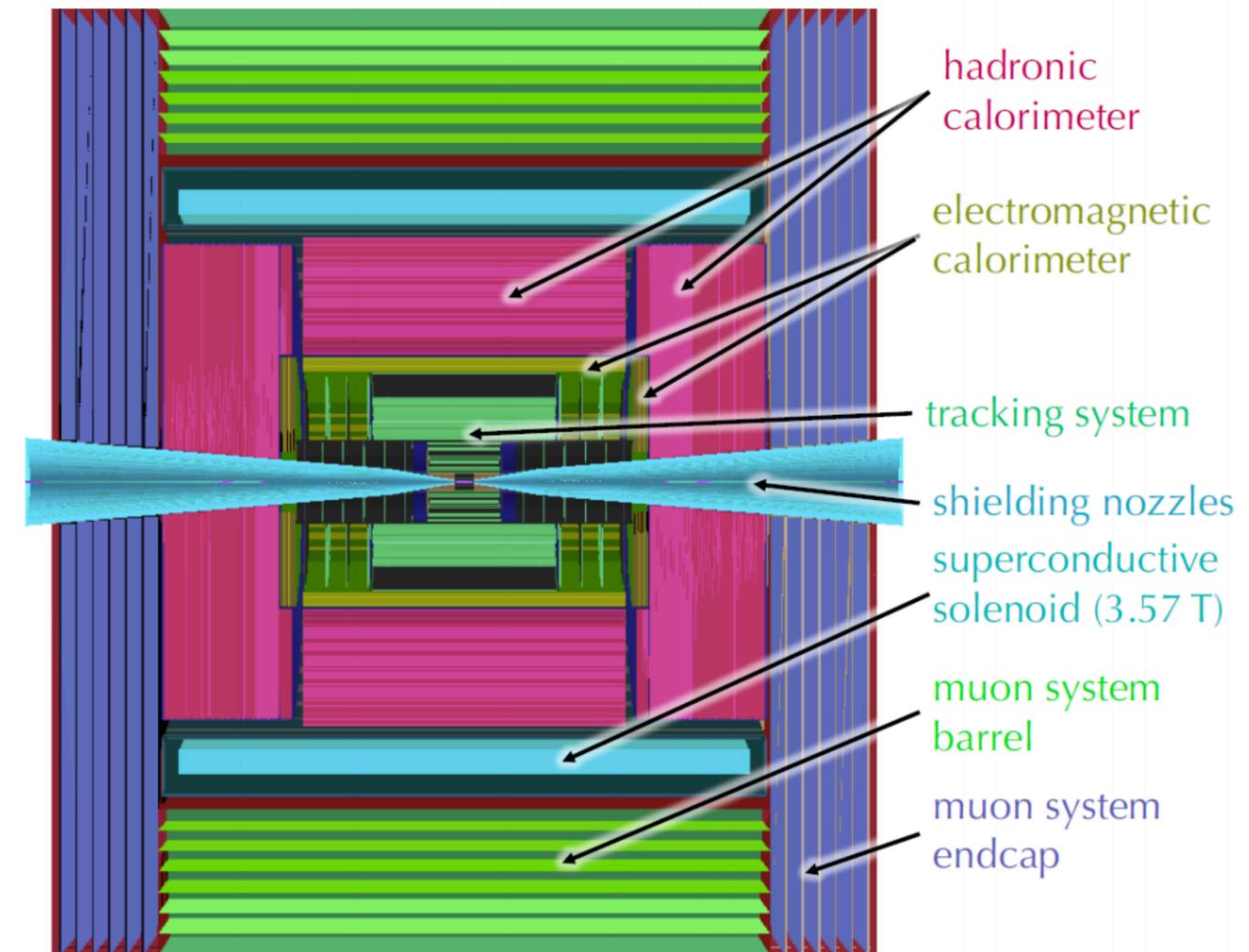
- Radiation hardness
 - LGAD-sensors ~ 25 ps for $50 \mu\text{m}$ sensors and $2 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$
 - 3D-trench Si sensors: $O(100)$ ps and a goal of $10^{16} - 10^{17} \text{ n}_{\text{eq}}/\text{cm}^2$
- “5D reconstruction”: space-points / ps-timing are available at each point along the track
 - LHCb EoI for LS4 is of general interest



More in Artur's talk tomorrow

Muon collider - detector requirements

- Beam Induced Background (BIB) in detector
 - $O(100)$ million (mostly soft) particles per beam crossing
 - 1% are charged
- Vertex tracker detector expected occupancy is x10 larger than CMS pixels in HL-LHC
- large bandwidth for sending data off the detector
- Emerging detector developments for the muon collider inspired to e+e- linear colliders
- CLIC Detector technologies adopted with important tracker modifications to cope with BIB
- Challenges for tracking system:
 - high number of BIB particles → Need high granularity (25-50 μ m), fast timing (20-30ps), intelligent readout, directional information

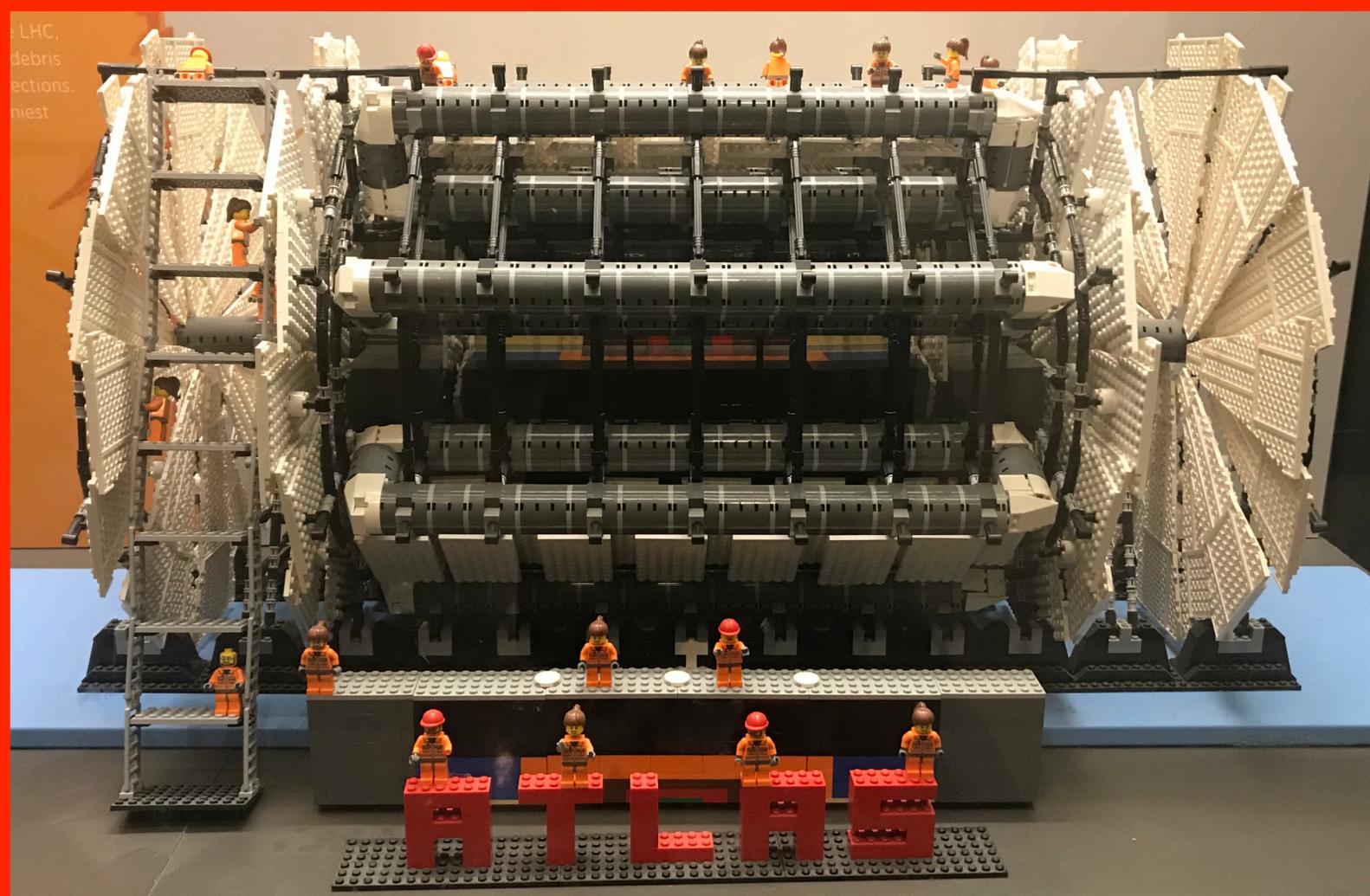


Nadia Pastrone, Feb 2021

- Future lepton colliders have the potential to develop high precision silicon detectors to help reach unprecedented physics goals
 - Requires excellent momentum and impact parameter resolution
 - Bunch time structure allows high precision trackers with very low X_0 at **linear lepton colliders**
- Pixel detectors with very fine pixel pitch, excellent single point resolution, and low X_0 required
 - Favors technologies which allow to focus on resolution and material budget
 - **Reaching the specifications all together is the real challenge**
- Advancements in timing sensors to get to radiation hard and O(10)ps resolution
 - 4D tracking (with precision timing information) potentially could be considered for e+e- - if the physics gain is significant with respect to increased material budget
- New ideas/technologies being explored for particle flow calorimetry : high precision (ps) timing calorimeters, new sensors ideas (ex: MAPS, LGADs) and dual readout technology

All these technologies being discussed within Snowmass21 as a follow up of the priority research directions (PRD) of the new DOE BRN report

- ECFA Detector R&D Process is expected to release the final report in the Fall 2021
 - describe diversified detector R&D portfolio that has the largest potential to enhance the performance of the particle physics program in the near and long term
 - Starting point is the the future science programs to identify :
 - main detector technology challenges
 - estimate the timelines of the required detector R&D programs



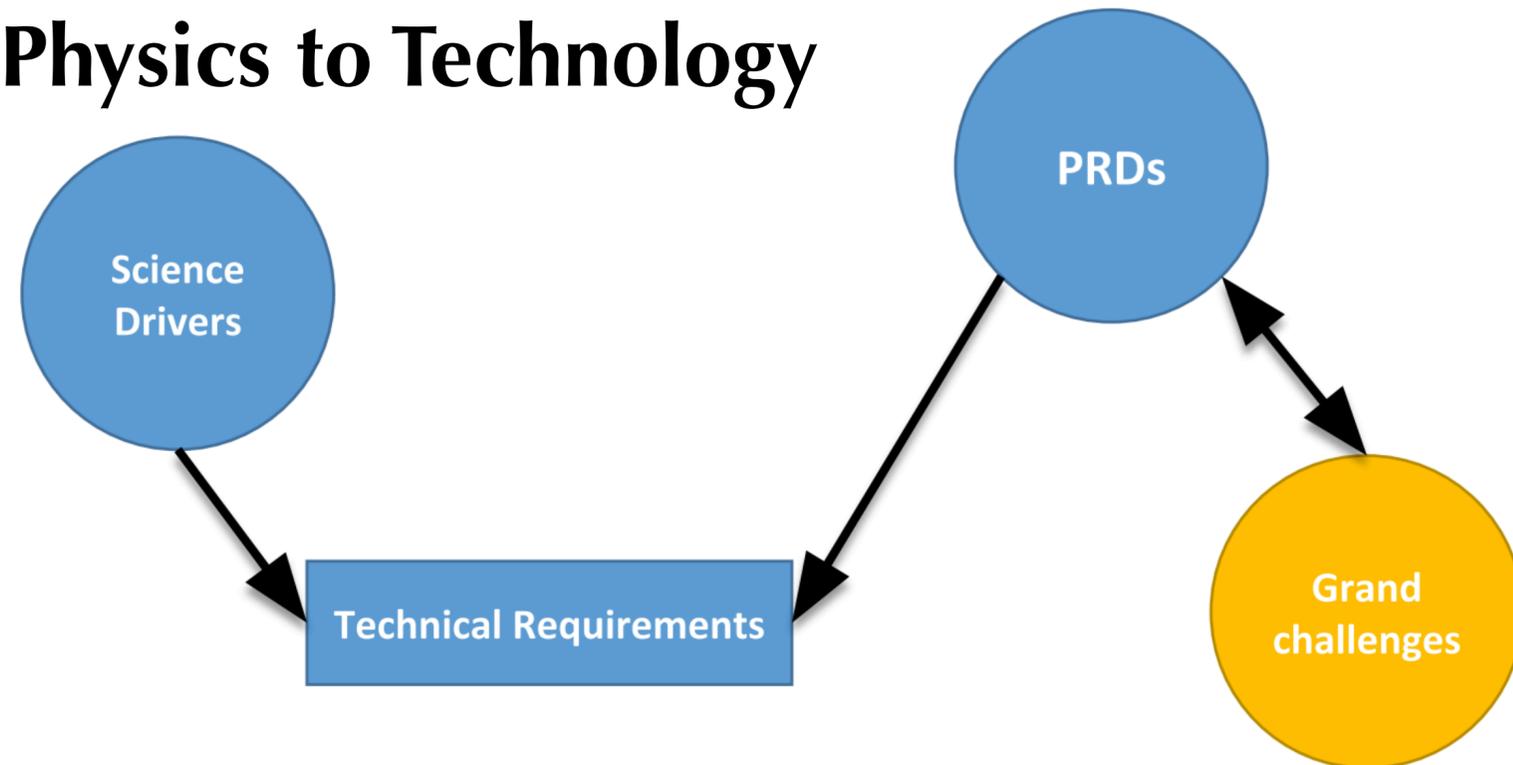
thank you!

- A class of BSM models predicts that the origin of the 1st and 2nd generation fermion masses is an additional source of EWSB, predicts large deviations from the SM values
 - Higgs to ss as well as cs at future colliders is the next milestone to probe the nature of Yukawa couplings
- Strange quarks mostly hadronize to prompt kaons which carry a large fraction of the jet momentum
 - The most powerful high momenta K^\pm tags with dedicated particle identification detectors may be an exclusive territory of **e+ e- colliders**
 - The leading V0 s (K^0 s and Λ) have a distinctive 2-prong vertices topology
- The use of **precise timing information** would become very relevant for flavor tagging and providing an additional handle for separation between light quarks.
 - intermediate momentum K^\pm ID from fast timing can become a significant contributor for b and c decays (s tag K^\pm could be too high momentum for timing)
 - Detector design have a role too in capturing the high momenta V0 s that can decay deep into the tracker
 - Investigate optimal configurations for 4D tracking at future e+e- machines

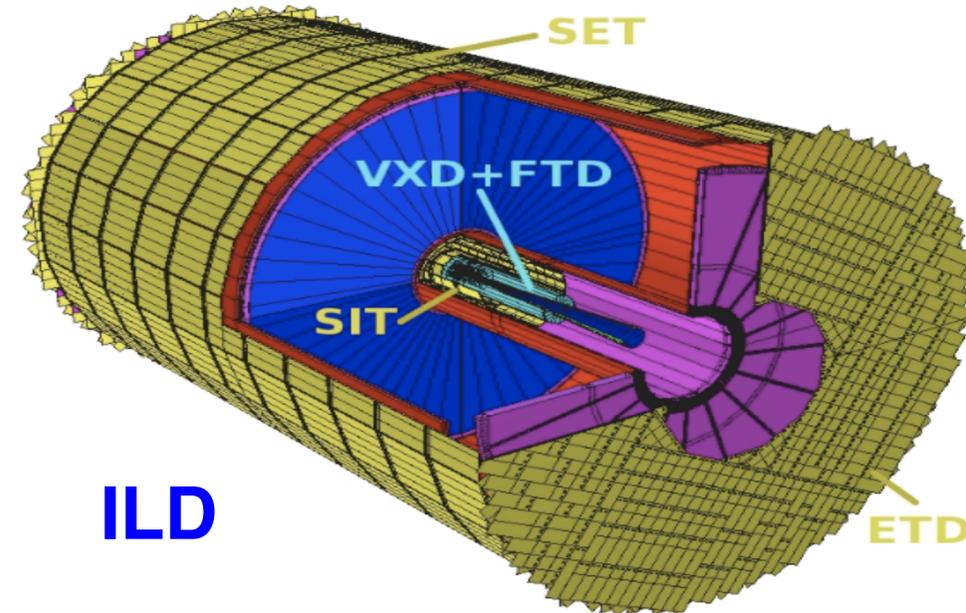
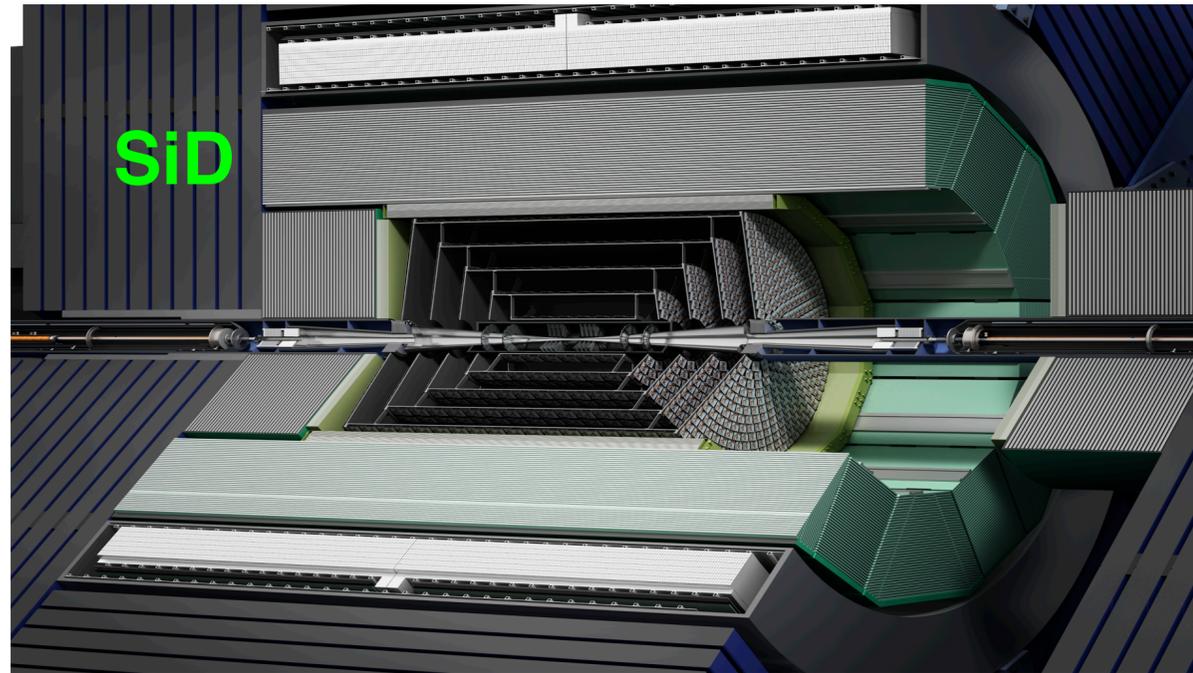
Four Grand Challenges for the Instrumentation revolution

- Advancing HEP detectors to new regimes of sensitivity
- Using Integration to enable scalability for HEP sensors
- Building next-generation HEP detectors with novel materials & advanced techniques
- Mastering extreme environments and data rates in HEP experiments

Physics to Technology

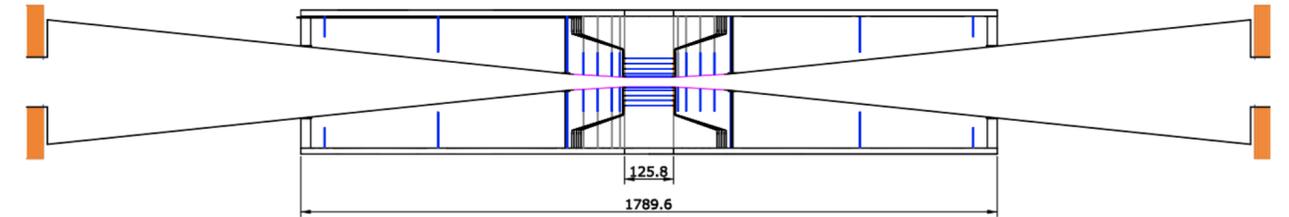


B. Fleming and I. Shipsey



- Future lepton colliders target unprecedented precision on physics \leftrightarrow extremely high precision detectors
- Silicon strip and pixel detectors are **key** for precision charged particle tracking, secondary vertexing, and as input to Particle Flow reconstruction - which is assumed as baseline
- Minimizing material budget is vital \rightarrow Exciting Si pixel & strip technologies in development

- Compact, cost constrained detector
 - 5 T solenoid B-field with $R_{ECAL}=1.27$ m
 - All silicon pixel vertex + tracking system
 - Highly granular Si calorimeter optimized for PFLOW
- Pixel Vertex detector
 - 1 kGy and 10^{11} n_{eq}/cm^2 per year
 - **Pixel hit resolution** better than $5 \mu m$ in barrel
 - Better if charge sharing is used
 - Less than **0.3% X_0** per pixel layer
 - air cooling \rightarrow low-mass sensor
 - Single bunch time resolution
 - Low capacitance and high S/N allows for acceptable power dissipation for single-crossing time resolution ($\sim 300-700$ ns)
- Outer pixel Tracker:
 - 0.1-0.15% X_0 in the central region



Barrel	R	z_{max}
Layer 1	14	63
Layer 2	22	63
Layer 3	35	63
Layer 4	48	63
Layer 5	60	63

Disk	R_{inner}	R_{outer}	z_{center}
Disk 1	14	71	72
Disk 2	16	71	92
Disk 3	18	71	123
Disk 4	20	71	172

Forward Disk	R_{inner}	R_{outer}	z_{center}
Disk 1	28	166	207
Disk 2	76	166	541
Disk 3	117	166	832

20x20 μm pixels in the central region
 50x50 μm for the forward tracker disks

